# LMR14050-Q1 SIMPLE SWITCHER® パワーコンバータ、40V、5A、車載用、40µA I_Q の降圧コンバータ

1 特長

- 車載アプリケーション認定済み
- 以下の結果で AEC-Q100 認定済み：
  - デバイス温度グレード 1：動作時周囲温度範囲 -40℃〜125℃
  - デバイス HBM ESD 分類レベル H1C
  - デバイス CDM ESD 分類レベル C4A
- 4V 〜 40V の入力電圧範囲
- 5A の連続出力電流
- 非常に小さい動作時静止電流：40µA
- 90mΩ ハイサイド MOSFET
- 最小スイッチ オン時間：75ns
- 電流モード制御
- 200kHz〜2.5MHz の可変スイッチング周波数
- 外部クロックへの周波数同期
- スペクトラム拡散オプションによる EMI 低減
- 使いやすさを実現した内部補償
- 高いデューティ サイクルでの動作をサポート
- 高精度イネーブル入力
- 1µA のシャットダウン電流
- 外部設定可能なソフト スタート
- 過熱 / 過電圧 / 短絡保護
- PowerPAD™ 付き 8 ピン HSOIC パッケージ

2 アプリケーション

- 車載用バッテリ レギュレーション
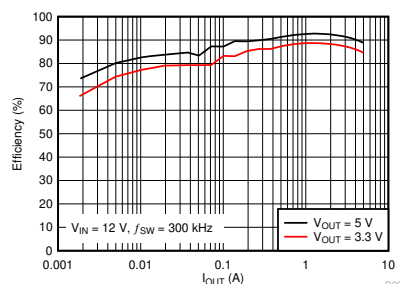- 産業用電源
- テレコムおよびデータコム システム
- 汎用の広範囲な VIN 変動率
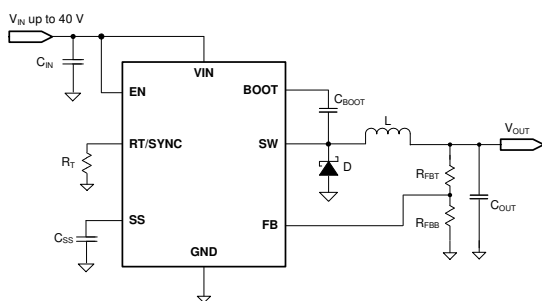
3 概要

LMR14050-Q1 は、ハイサイド MOSFET を内蔵した 40V、5A の降圧レギュレータです。4V〜40V という幅広い入力範囲により、産業用から車載用まで、非レギュレーション電源からの電源調整を行うさまざまなアプリケーション向けに設計されています。広範な製品ファミリには、LMR14020-Q1 と LMR14030-Q1 を含む 2A、3.5A の負荷製品がピン互換のパッケージで供給されています。本レギュレータのスリープ モードの静止電流は 40µA であり、バッテリ駆動システムに適しています。シャットダウン モードの電流も 1µA ときわめて低いことから、バッテリ駆動時間のさらなる延長が可能です。調整可能なスイッチング周波数の範囲が広いため、効率と外付け部品のサイズを最適化できます。内部ループ補償により、ユーザーはループ補償を設計する煩雑な作業から解放されます。また、本デバイスの外付け部品の数も最小限で済みます。高精度のイネーブル入力により、レギュレータの制御とシステムの電源シーケンスが単純化されます。このデバイスには、サイクル単位の電流制限、熱センシング、過剰な消費電力によるサーマル シャットダウン、出力過電圧保護などの保護機能も組み込まれています。

LMR14050-Q1 は、熱抵抗を下げるための露出パッドを備えた 8 ピン HSOIC または 10 ピン WSON パッケージで供給されます。

製品情報

部品番号	パッケージ[1]	パッケージ サイズ[2]
LMR14050SQDDARQ1	DDA (HSOIC、8)	4.9mm × 6mm
LMR14050SSQDDARQ1 (スペクトラム拡散)		
LMR14050QDPRRQ1	DPR (WSON、10)	4mm × 4mm
LMR14050SQDPRRQ1 (スペクトラム拡散)		

(1) 詳細については、セクション 10 を参照してください。
(2) パッケージ サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。

概略回路図

効率と出力電流との関係

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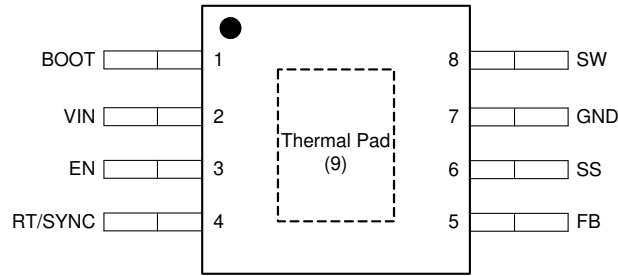English Data Sheet: SNVSAG2

4 Pin Configuration and Functions

図 4-1. DDA Package 8-Pin (HSOIC) Top View
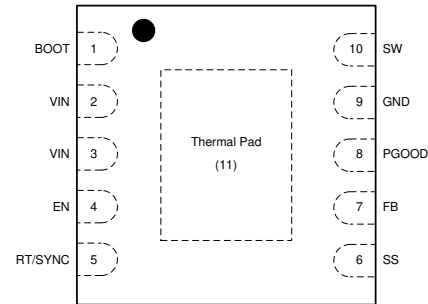
図 4-2. DPR Package 10-Pin (WSON) Top View

表 4-1. Pin Functions

NAME	NO.		TYPE [1]	DESCRIPTION
	SO-8	WSON-10		
BOOT	1	1	P	Bootstrap capacitor connection for high-side MOSFET driver. Connect a high quality 0.1 µF capacitor from BOOT to SW.
VIN	2	2, 3	P	Connect to power supply and bypass capacitors C_{IN}. Path from VIN pin to high frequency bypass C_{IN} and GND must be as short as possible.
EN	3	4	A	Enable pin, with internal pull-up current source. Pull below 1.2 V to disable. Float or connect to VIN to enable. Adjust the input under voltage lockout with two resistors. See the Enable and Adjusting Under voltage lockout section.
RT/SYNC	4	5	A	Resistor Timing or External Clock input. An internal amplifier holds this pin at a fixed voltage when using an external resistor to ground to set the switching frequency. If the pin is pulled above the PLL upper threshold, a mode change occurs and the pin becomes a synchronization input. The internal amplifier is disabled and the pin is a high impedance clock input to the internal PLL. If clocking edges stop, the internal amplifier is re-enabled and the operating mode returns to frequency programming by resistor.
FB	5	7	A	Feedback input pin, connect to the feedback divider to set V_{OUT}. Do not short this pin to ground during operation.
SS	6	6	A	Soft-start control pin. Connect to a capacitor to set soft-start time.
PGOOD	N/A	8	A	Open drain output for power-good flag. Use a 10 kΩ to 100 kΩ pull-up resistor to logic rail or other DC voltage no higher than 7V.
GND	7	9	G	System ground pin.
SW	8	10	P	Switching output of the regulator. Internally connected to high-side power MOSFET. Connect to power inductor.
Thermal Pad	9	11	G	Major heat dissipation path of the die. Must be connected to ground plane on PCB.

(1) A = Analog, P = Power, G = Ground

資料に関するフィードバック(ご意見やお問い合わせ)を送信

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English Data Sheet: SNVSAG2

5 Specifications

5.1 Absolute Maximum Ratings

Over the recommended operating junction temperature range of –40°C to 125°C (unless otherwise noted) [1]

		MIN	MAX	UNIT
Input voltages	VIN, EN to GND	–0.3	44	V
	BOOT to GND	–0.3	49	
	SS to GND	–0.3	5	
	FB to GND (DPR package)	–0.3	7	
	FB to GND (DDA package)	–0.3	5.5	
	RT/SYNC to GND	–0.3	3.6	
	PGOOD to GND	–0.3	7	
Output voltages	BOOT to SW (DPR package)		6.5	V
	BOOT to SW (DDA package)		5.5	
	SW to GND	–3	44	
T_J	Junction temperature	–40	150	°C
T_{stg}	Storage temperature	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 [1]	±2000	V
		Charged-device model (CDM), per AEC Q100-011	±750	

(1) AEC Q100-002 indicates that HBM stressing must be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

5.3 Recommended Operating Conditions

Over the recommended operating junction temperature range of –40°C to 125°C (unless otherwise noted) [1]

		MIN	MAX	UNIT
Buck regulator	VIN	4	40	V
	VOUT	0.8	28	
	BOOT		45	
	SW	–1	40	
	FB	0	5	
Control	EN	0	40	V
	RT/SYNC	0	3.3	
	SS	0	3	
	PGOOD to GND	0	5	
Frequency	Switching frequency range at RT mode	200	2500	kHz
	Switching frequency range at SYNC mode	250	2300	
Temperature	Operating junction temperature, T_J	–40	125	°C

(1) Operating Ratings indicate conditions for which the device is intended to be functional, but do not specify specific performance limits. For specified specifications, see *セクション 5.5* .

5.4 Thermal Information

THERMAL METRIC [1] [2]		LMR14050-Q1		UNIT
		DDA (HSOIC)	DPR (WSON)	
		8 PINS	10 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	43.2	36.5	°C/W
ψ_{JT}	Junction-to-top characterization parameter	5.2	0.3	°C/W
ψ_{JB}	Junction-to-board characterization parameter	16.4	13.8	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	52.1	35.2	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	7.8	3.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	16.4	13.6	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application note.

(2) Power rating at a specific ambient temperature T_A must be determined with a maximum junction temperature (T_J) of 125°C, which is illustrated in *Recommended Operating Conditions* section.

5.5 Electrical Characteristics

Limits apply over the recommended operating junction temperature (T_J) range of –40°C to +125°C, unless otherwise stated. Minimum and Maximum limits are specified through test, design or statistical correlation. Typical values represent the most likely parametric norm at T_J = 25°C, and are provided for reference purposes only. Unless otherwise specified, the following conditions apply: V_{IN} = 4.0 V to 40 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLY (VIN PIN)						
V_{IN}	Operation input voltage		4		40	V
UVLO	Undervoltage lockout thresholds	Rising threshold	3.5	3.7	3.9	V
		Hysteresis		285		mV
I_{SHDN}	Shutdown supply current	V_{EN} = 0 V, T_J = 25°C, 4.0 V ≤ V_{IN} ≤ 40 V		1.0	3.0	µA
I_Q	Operating quiescent current (non-switching)	V_{FB} = 1.0 V, T_J = 25°C		40		µA
ENABLE (EN PIN)						
V_{EN_TH}	EN threshold voltage		1.05	1.20	1.38	V
I_{EN_PIN}	EN PIN current	Enable threshold +50 mV		–4.6		µA
		Enable threshold –50 mV		–1.0		
I_{EN_HYS}	EN hysteresis current			–3.6		µA
EXTERNAL SOFT-START						
I_{SS}	SS pin current	T_J = 25°C		–3		µA
POWER GOOD (PGOOD PIN)						
V_{PG_UV}	Power-good flag under voltage tripping threshold	POWER GOOD (% of FB voltage)		94%		
		POWER BAD (% of FB voltage)		92%		
V_{PG_OV}	Power-good flag over voltage tripping threshold	POWER BAD (% of FB voltage)		109%		
		POWER GOOD (% of FB voltage)		107%		
V_{PG_HYS}	Power-good flag recovery hysteresis	% of FB voltage		2%		
I_{PG}	PGOOD leakage current at high level output	$V_{Pull-Up}$ = 5 V		10	200	nA
V_{PG_LOW}	PGOOD low level output voltage	$I_{Pull-Up}$ = 1 mA		0.1		V
$V_{IN\_PG\_MIN}$	Minimum VIN for valid PGOOD output	$V_{Pull-Up}$ < 5 V at $I_{Pull-Up}$ = 100 µA		1.6	1.95	V
VOLTAGE REFERENCE (FB PIN)						
V_{FB}	Feedback voltage	T_J = 25°C	0.744	0.750	0.756	V
		T_J = -40 °C to 125 °C	0.735	0.750	0.765	V

5.5 Electrical Characteristics (続き)

Limits apply over the recommended operating junction temperature (T_J) range of –40°C to +125°C, unless otherwise stated. Minimum and Maximum limits are specified through test, design or statistical correlation. Typical values represent the most likely parametric norm at T_J = 25°C, and are provided for reference purposes only. Unless otherwise specified, the following conditions apply: V_{IN} = 4.0 V to 40 V

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
HIGH-SIDE MOSFET						
R_{DS_ON}	On-resistance	V_{IN} = 12 V		90	180	mΩ
HIGH-SIDE MOSFET CURRENT LIMIT						
I_{LIMT}	Current limit	V_{IN} = 12 V, T_J = –40°C to 125°C, Open Loop	5.8	7.9	10.9	A
THERMAL PERFORMANCE						
T_{SHDN}	Thermal shutdown threshold			170		°C
T_{HYS}	Hysteresis			12		

5.6 Switching Characteristics

Over the recommended operating junction temperature range of –40°C to 125°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{SW}	Switching frequency	R_T = 11.5 kΩ	1758	1912	2066	kHz
	Switching frequency range at SYNC mode		250		2300	
F_{DITHER}	Switching frequency dithering	Spread spectrum option, frequency dithering over center frequency		±6%		
V_{SYNC_HI}	SYNC clock high level threshold		1.7			V
V_{SYNC_LO}	SYNC clock low level threshold				0.5	
T_{SYNC_MIN}	Minimum SYNC input pulse width	Measured at 500 kHz, V_{SYNC_HI} > 3 V, V_{SYNC_LO} < 0.3 V		30		ns
T_{LOCK_IN}	PLL lock in time	Measured at 500 kHz		100		µs
T_{ON_MIN}	Minimum controllable on time	V_{IN} = 12 V, I_{Load} = 1 A		75		ns
D_{MAX}	Maximum duty cycle	f_{SW} = 200 kHz		97%		

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5.7 Typical Characteristics

Unless otherwise specified the following conditions apply: V_{IN} = 12 V, f_{SW} = 300 kHz, L = 6.5 µH, C_{OUT} = 47 µF × 4, T_A = 25°C

V_{OUT} = 5 V f_{SW} = 300 kHz
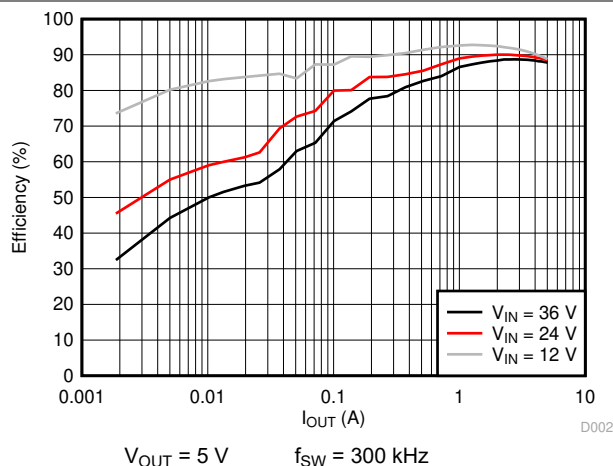
図 5-1. Efficiency vs. Load Current

V_{OUT} = 5 V f_{SW} = 500 kHz
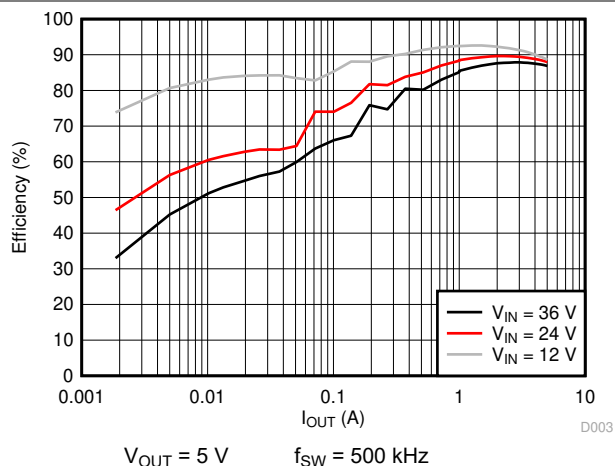
図 5-2. Efficiency vs. Load Current

V_{OUT} = 3.3 V f_{SW} = 300 kHz
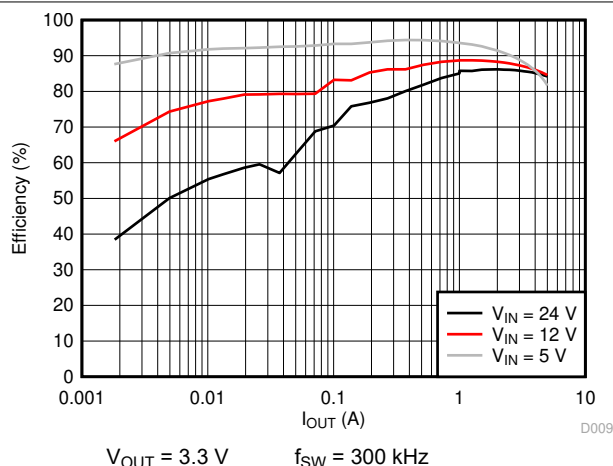
図 5-3. Efficiency vs. Load Current

V_{OUT} = 3.3 V f_{SW} = 500 kHz
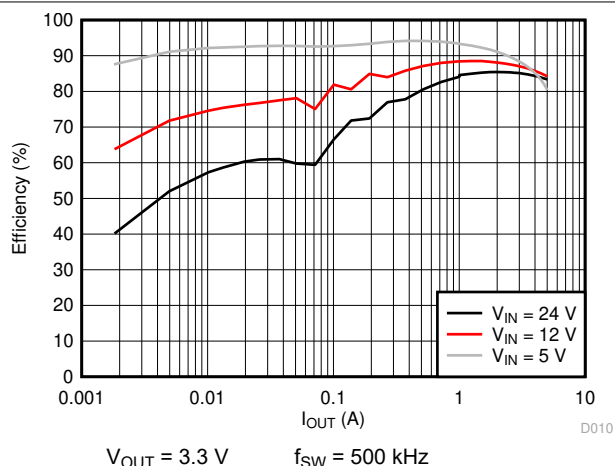
図 5-4. Efficiency vs. Load Current
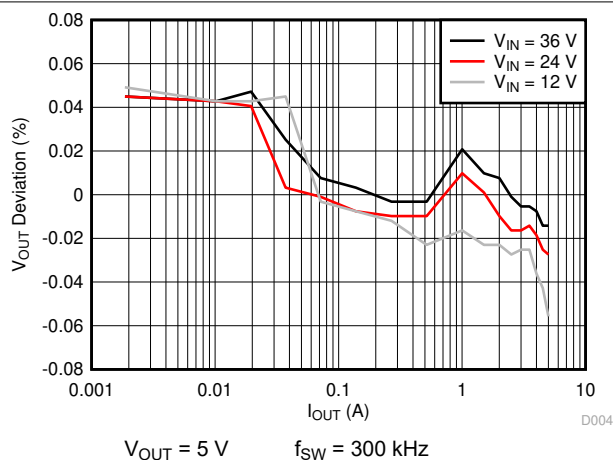

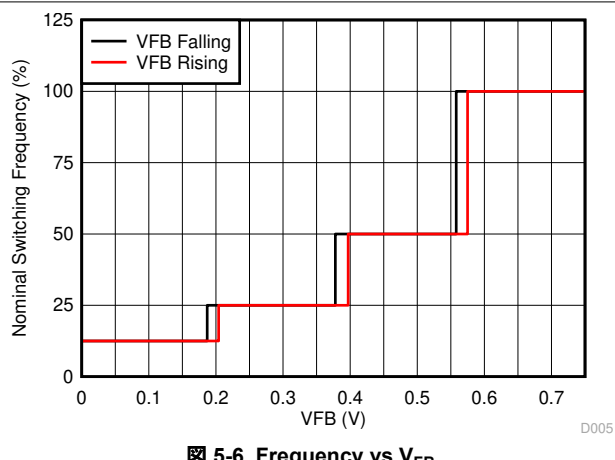V_{OUT} = 5 V f_{SW} = 300 kHz

図 5-5. Load Regulation

図 5-6. Frequency vs V_{FB}

5.7 Typical Characteristics (continued)

Unless otherwise specified the following conditions apply: V_{IN} = 12 V, f_{SW} = 300 kHz, L = 6.5 µH, C_{OUT} = 47 µF × 4, T_A = 25°C

V_{OUT} = 5 V f_{SW} = 300 kHz

図 5-7. Dropout Curve

V_{OUT} = 5 V f_{SW} = 500 KHz

図 5-8. Dropout Curve

V_{OUT} = 3.3 V f_{SW} = 300 kHz

図 5-9. Dropout Curve

V_{OUT} = 3.3 V f_{SW} = 500 kHz
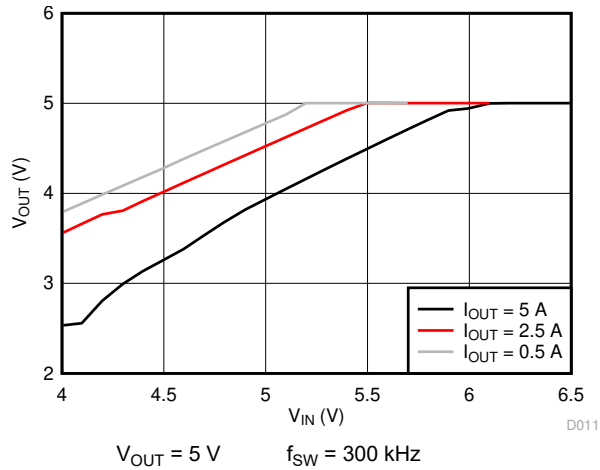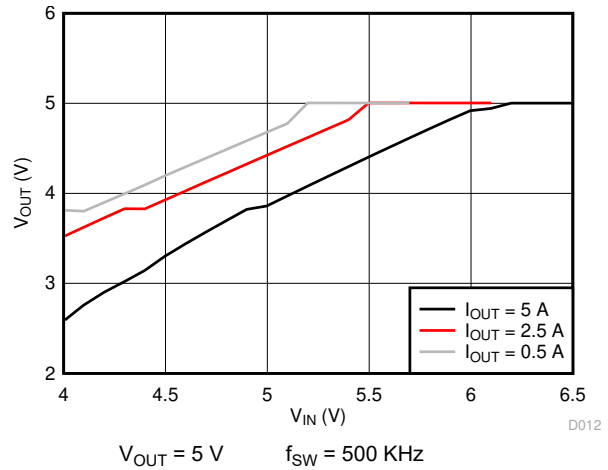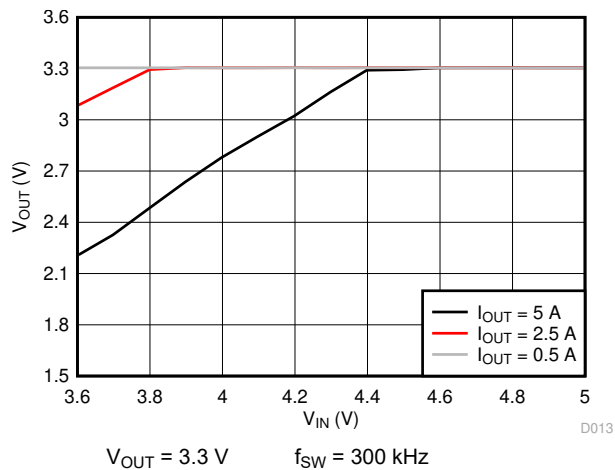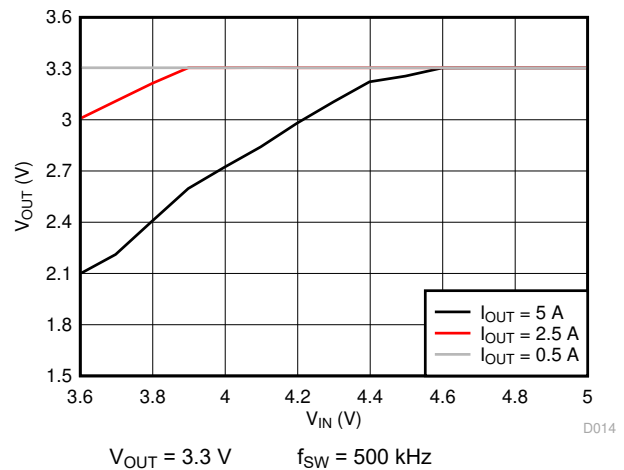
図 5-10. Dropout Curve
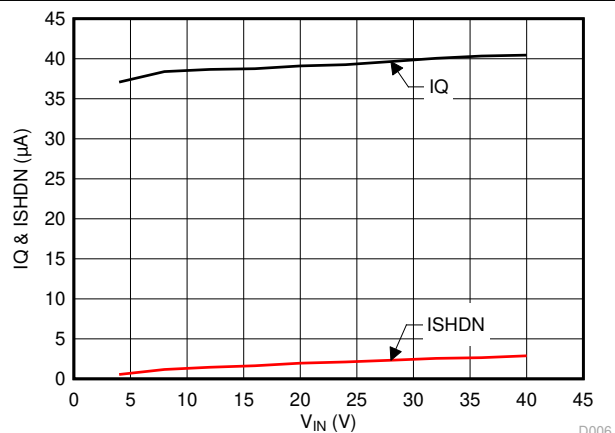
図 5-11. Shut-down Current and Quiescent Current

I_{OUT} = 0 A

図 5-12. UVLO Threshold

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6 Detailed Description

6.1 Overview

The LMR14050-Q1 SIMPLE SWITCHER® power converter regulator is an easy to use step-down DC-DC converter that operates from a 4.0 V to 40 V supply voltage. The device integrates a 90 mΩ (typical) high-side MOSFET, and is capable of delivering up to 5 A DC load current with exceptional efficiency and thermal performance in a very small design size. The operating current is typically 40 µA under no load condition (not switching). When the device is disabled, the supply current is typically 1 µA. An extended family is available in 2 A and 3.5 A load options in pin to pin compatible packages.

The LMR14050-Q1 implements constant frequency peak current mode control with sleep mode at light load to achieve high efficiency. The device is internally compensated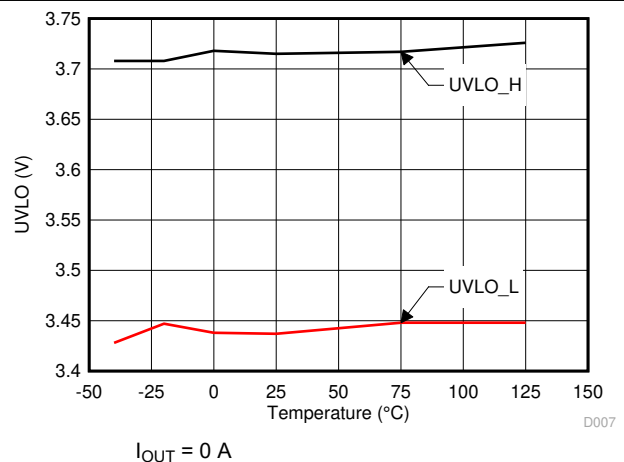, which reduces design time, and requires fewer external components. The switching frequency is programmable from 200 kHz to 2.5 MHz by an external resistor R_T. The LMR14050-Q1 is also capable of synchronization to an external clock within the 250 kHz to 2.3 MHz frequency range, which allows the device to be optimized to fit small board space at higher frequency, or high efficient power conversion at lower frequency.

Other features are included for more comprehensive system requirements, including precision enable, adjustable soft-start time, and approximate 97% duty cycle by BOOT capacitor recharge circuit. These features provide a flexible and easy to use platform for a wide range of applications. Protection features include over temperature shutdown, V_{OUT} over voltage protection (OVP), V_{IN} under-voltage lockout (UVLO), cycle-by-cycle current limit, and short-circuit protection with frequency fold-back.

6.2 Functional Block Diagram

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English Data Sheet: SNVSAG2
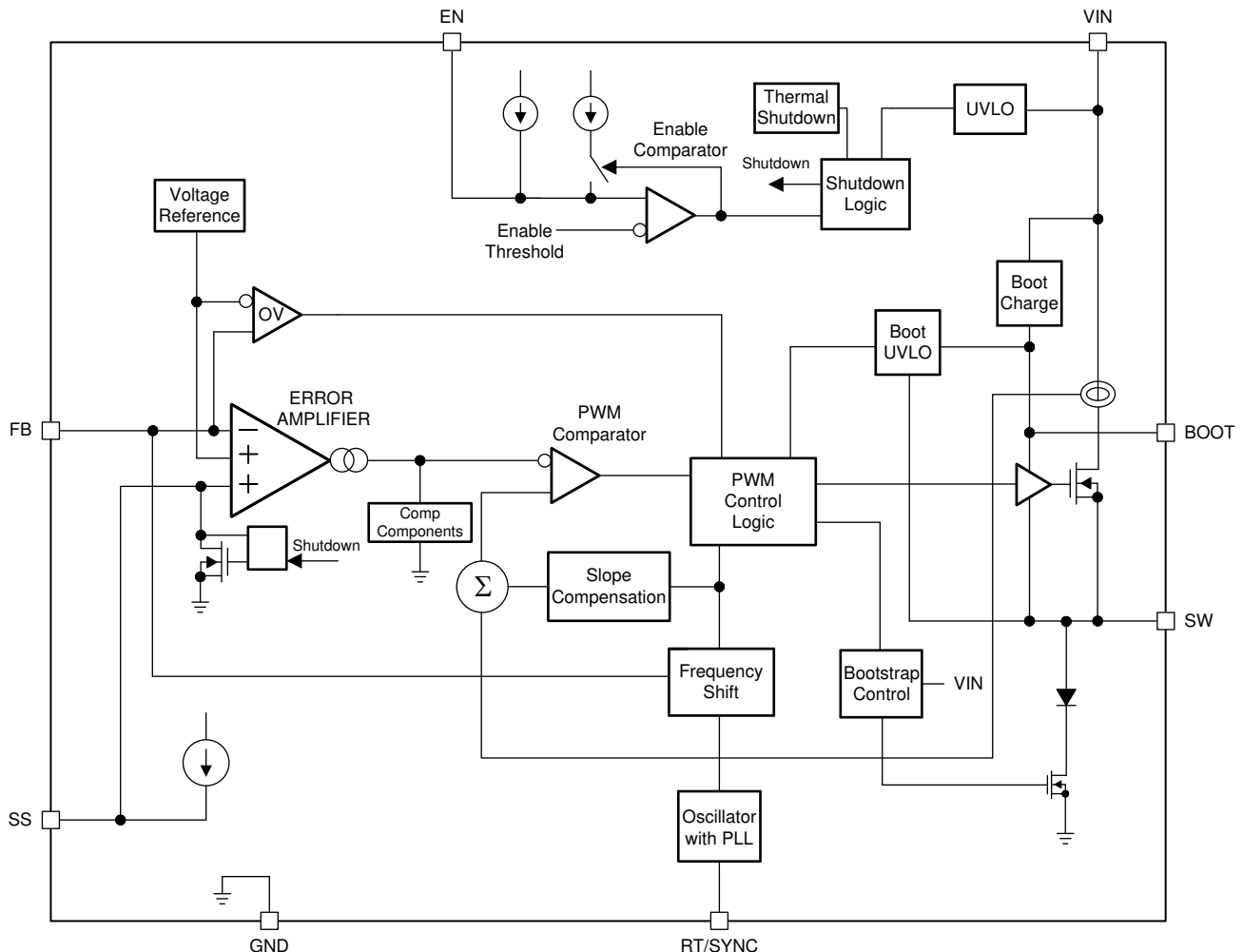
6.3 Feature Description

6.3.1 Fixed Frequency Peak Current Mode Control

The following operating description of the LMR14050-Q1 refers to the *セクション 6.2* and to the waveforms in *図 6-1*. LMR14050-Q1 output voltage is regulated by turning on the high-side N-MOSFET with controlled ON time. During high-side switch ON time, the SW pin voltage swings up to approximately V_{IN}, and the inductor current i_L increase with linear slope $(V_{IN} - V_{OUT}) / L$. When high-side switch is off, inductor current discharges through freewheel diode with a slope of $-V_{OUT} / L$. The control parameter of Buck converter is defined as Duty Cycle D = t_{ON} / T_{SW}, where t_{ON} is the high-side switch ON time and T_{SW} is the switching period. The regulator control loop maintains a constant output voltage by adjusting the duty cycle D. In an ideal Buck converter, where losses are ignored, D is proportional to the output voltage and inversely proportional to the input voltage: D = V_{OUT} / V_{IN}.
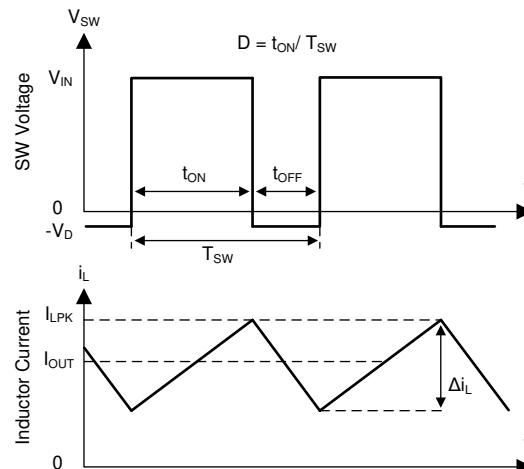
図 6-1. SW Node and Inductor Current Waveforms in Continuous Conduction Mode (CCM)

The LMR14050-Q1 employs fixed frequency peak current mode control. A voltage feedback loop is used to get accurate DC voltage regulation by adjusting the peak current command based on voltage offset. The peak inductor current is sensed from the high-side switch and compared to the peak current to control the ON time of the high-side switch. The voltage feedback loop is internally compensated, which allows for fewer external components, making design easy, and provides stable operation with almost any combination of output capacitors. The regulator operates with fixed switching frequency at normal load condition. At very light load, the LMR14050-Q1 will operate in Sleep-mode to maintain high efficiency and the switching frequency will decrease with reduced load current.

6.3.2 Slope Compensation

The LMR14050-Q1 adds a compensating ramp to the MOSFET switch current sense signal. This slope compensation prevents sub-harmonic oscillations at duty cycles greater than 50%. The peak current limit of the high-side switch is not affected by the slope compensation and remains constant over the full duty cycle range.

6.3.3 Sleep-mode

The LMR14050-Q1 operates in Sleep-mode at light load currents to improve efficiency by reducing switching and gate drive losses. If the output voltage is within regulation and the peak switch current at the end of any switching cycle is below the current threshold of 300 mA, the device enters Sleep-mode. The Sleep-mode current threshold is the peak switch current level corresponding to a nominal internal COMP voltage of 400 mV.

When in Sleep-mode, the internal COMP voltage is clamped at 400 mV and the high-side MOSFET is inhibited, and the device draws only 40 µA (typical) input quiescent current. Since the device is not switching, the output voltage begins to decay. The voltage control loop responds to the falling output voltage by increasing the internal COMP voltage. The high-side MOSFET is enabled and switching resumes when the error amplifier lifts internal

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COMP voltage above 400 mV. The output voltage recovers to the regulated value, and internal COMP voltage eventually falls below the Sleep-mode threshold at which time the device again enters Sleep-mode.

6.3.4 Low Dropout Operation and Bootstrap Voltage (BOOT)

The LMR14050-Q1 provides an integrated bootstrap voltage regulator. A small capacitor between the BOOT and SW pins provides the gate drive voltage for the high-side MOSFET. The BOOT capacitor is refreshed when the high-side MOSFET is off and the external low side diode conducts. The recommended value of the BOOT capacitor is 0.1 μF. TI recommends a ceramic capacitor with an X7R or X5R grade dielectric with a voltage rating of 16 V or greater for stable performance over temperature and voltage.

When operating with a low voltage difference from input to output, the high-side MOSFET of the LMR14050-Q1 operates at approximate 97% duty cycle. When the high-side MOSFET is continuously on for 5 or 6 switching cycles (5 or 6 switching cycles for frequency lower than 1 MHz, and 10 or 11 switching cycles for frequency higher than 1 MHz) and the voltage from BOOT to SW drops below 3.2 V, the high-side MOSFET is turned off and an integrated low side MOSFET pulls SW low to recharge the BOOT capacitor.

Since the gate drive current sourced from the BOOT capacitor is small, the high-side MOSFET can remain on for many switching cycles before the MOSFET is turned off to refresh the capacitor. Thus the effective duty cycle of the switching regulator can be high, approaching 97%. The effective duty cycle of the converter during dropout is mainly influenced by the voltage drops across the power MOSFET, the inductor resistance, the low side diode voltage and the printed circuit board resistance.

6.3.5 Adjustable Output Voltage

The internal voltage reference produces a precise 0.75 V (typical) voltage reference over the operating temperature range. The output voltage is set by a resistor divider from output voltage to the FB pin. TI recommends to use 1% tolerance or better and temperature coefficient of 100 ppm or less divider resistors. Select the low side resistor R_{FBB} for the desired divider current and use 式 1 to calculate high-side R_{FBT}. Larger value divider resistors are good for efficiency at light load. However, if the values are too high, the regulator is more susceptible to noise and voltage errors from the FB input current can become noticeable. TI recommends R_{FBB} in the range from 10 kΩ to 100 kΩ for most applications.
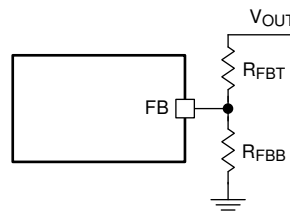

図 6-2. Output Voltage Setting

$$R_{FBT} = \frac{V_{OUT} - 0.75}{0.75} \times R_{FBB}$$

(1)

6.3.6 Enable and Adjustable Undervoltage Lockout

The LMR14050-Q1 is enabled when the VIN pin voltage rises above 3.7 V (typical) and the EN pin voltage exceeds the enable threshold of 1.2 V (typical). The LMR14050-Q1 is disabled when the VIN pin voltage falls below 3.42 V (typical) or when the EN pin voltage is below 1.2 V. The EN pin has an internal pullup current source (typically I_{EN} = 1 μA) that enables operation of the LMR14050-Q1 when the EN pin is floating.

Many applications benefit from the employment of an enable divider R_{ENT} and R_{ENB} in 図 6-1 to establish a precision system UVLO level for the stage. System UVLO can be used for supplies operating from utility power as well as battery power. System UVLO can be used for sequencing, making sure of reliable operation, or supply protection, such as a battery. An external logic signal can also be used to drive EN input for system sequencing and protection.

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When EN terminal voltage exceeds 1.2 V, an additional hysteresis current (typically I_{HYS} = 3.6 µA) is sourced out of EN terminal. When the EN terminal is pulled below 1.2 V, I_{HYS} current is removed. This additional current facilitates adjustable input voltage UVLO hysteresis. Use 式 2 and 式 3

式 3 to calculate R_{ENT} and R_{ENB} for desired UVLO hysteresis voltage.
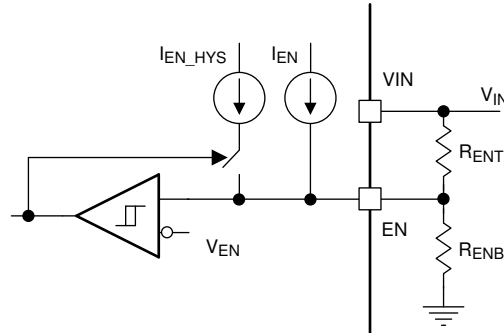

図 6-3. System UVLO By Enable Dividers

$$R_{ENT} = \frac{V_{START} - V_{STOP}}{I_{HYS}}$$

(2)

$$R_{ENB} = \frac{V_{EN}}{\dfrac{V_{START} - V_{EN}}{R_{ENT}} + I_{EN}}$$

(3)

where V_{START} is the desired voltage threshold to enable LMR14050-Q1, V_{STOP} is the desired voltage threshold to disable device.

6.3.7 External Soft-start

The LMR14050-Q1 has soft-start pin for programmable output ramp up time. The soft-start feature is used to prevent inrush current impacting the LMR14050-Q1 and the load when power is first applied. The soft-start time can be programed by connecting an external capacitor C_{SS} from SS pin to GND. An internal current source (typically I_{SS} = 3 µA) charges C_{SS} and generates a ramp from 0 V to V_{REF}. The soft-start time can be calculated by 式 4:

$$t_{SS}(ms) = \frac{C_{SS}(nF) \times V_{REF}(V)}{I_{SS}(\mu A)}$$

(4)

For LMR14050-Q1 in WSON package, the maximum value of C_{SS} is 4.7 nF

The soft-start resets while device is disabled or in thermal shutdown.

6.3.8 Switching Frequency and Synchronization (RT/SYNC)

The switching frequency of the LMR14050-Q1 can be programmed by the resistor RT from the RT/SYNC pin and GND pin. The RT/SYNC pin can't be left floating or shorted to ground. To determine the timing resistance for a given switching frequency, use 式 5 or the curve in 図 6-4. 表 6-1 gives typical R_T values for a given f_{SW}.
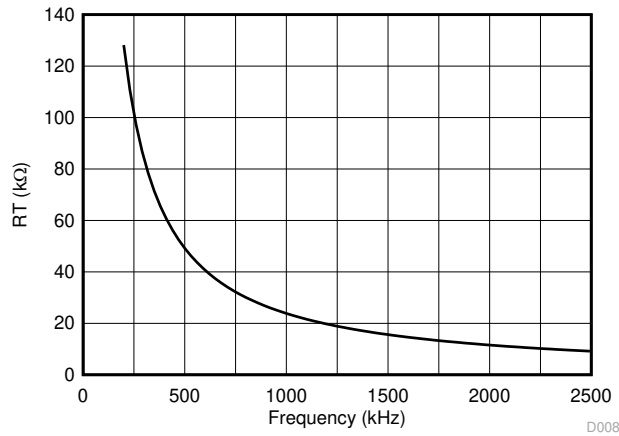
$$R_T(k\Omega) = 42904 \times f_{SW}(kHz)^{-1.088}$$

(5)

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図 6-4. R_T vs Frequency Curve

表 6-1. Typical Frequency Setting R_T Resistance

f_{SW} (kHz)	R_T (kΩ)
200	133
350	73.2
500	49.9
750	32.4
1000	23.2
1500	15.0
1912	11.5
2200	9.76

The LMR14050-Q1 switching action can also be synchronized to an external clock from 250 kHz to 2.3 MHz. Connect a square wave to the RT/SYNC pin through either circuit network shown in 図 6-5. Internal oscillator is synchronized by the falling edge of external clock. The recommendations for the external clock include: high level no lower than 1.7 V, low level no higher than 0.5 V and have a pulse width greater than 30 ns. When using a low impedance signal source, the frequency setting resistor R_T is connected in parallel with an AC coupling capacitor C_{COUP} to a termination resistor R_{TERM} (that is, 50 Ω). The two resistors in series provide the default frequency setting resistance when the signal source is turned off. A 10 pF ceramic capacitor can be used for C_{COUP}. 図 6-6, 図 6-7 and 図 6-8 show the device synchronized to an external system clock.
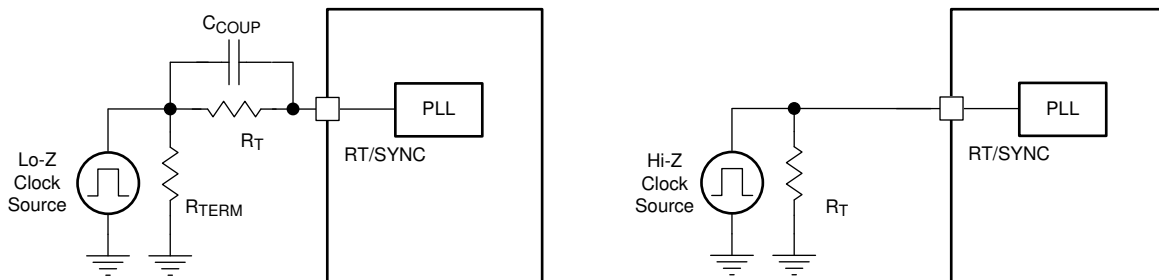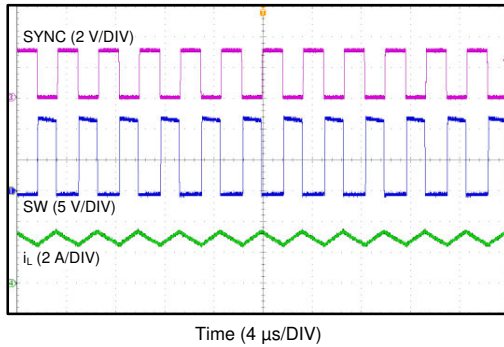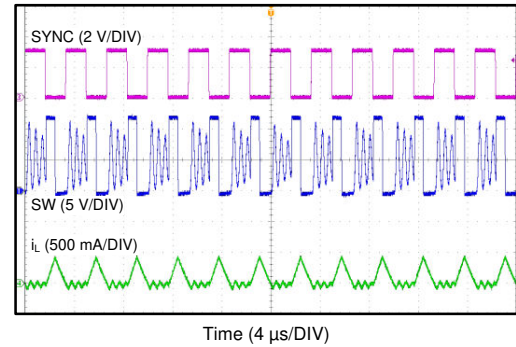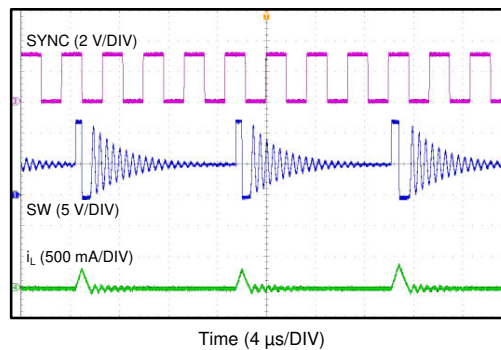

図 6-5. Synchronizing to an External Clock

図 6-6. Synchronizing in CCM

図 6-7. Synchronizing in DCM

図 6-8. Synchronizing in Sleep-mode Mode

For spread spectrum option, the internal frequency dithering is disabled if the device is synchronized to an external clock.

式 6 calculates the maximum switching frequency limitation set by the minimum controllable on time and the input to output step down ratio. Setting the switching frequency above this value causes the regulator to skip switching pulses to achieve the low duty cycle required at maximum input voltage.

$$f_{SW(max)} = \frac{1}{t_{ON}} \times \left(\frac{I_{OUT} \times R_{IND} + V_{OUT} + V_D}{V_{IN\_MAX} - I_{OUT} \times R_{DS\_ON} + V_D} \right)$$

(6)

where

- I_{OUT} = Output current
- R_{IND} = Inductor series resistance
- V_{IN_MAX} = Maximum input voltage
- V_{OUT} = Output voltage
- V_D = Diode voltage drop
- R_{DS_ON} = High-side MOSFET switch on resistance
- t_{ON} = Minimum on time

6.3.9 Power Good (PGOOD)

The LMR14020-Q1 in WSON-10 package has a built in power-good flag shown on PGOOD pin to indicate whether the output voltage is within the regulation level. The PGOOD signal can be used for start-up sequencing of multiple rails or fault protection. The PGOOD pin is an open-drain output that requires a pull-up resistor to an

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appropriate DC voltage. Voltage seen by the PGOOD pin must never exceed 7 V. A resistor divider pair can be used to divide the voltage down from a higher potential. A typical range of pullup resistor value is 10 kΩ to 100 kΩ.

Refer to 図 6-9. When the FB voltage is within the power-good band, +7% above and -6% below the internal reference V_{REF} typically, the PGOOD switch is turned off and the PGOOD voltage is pulled up to the voltage level defined by the pullup resistor or divider. When the FB voltage is outside of the tolerance band, +9% above or -8% below V_{REF} typically, the PGOOD switch is turned on and the PGOOD pin voltage is pulled low to indicate power bad.
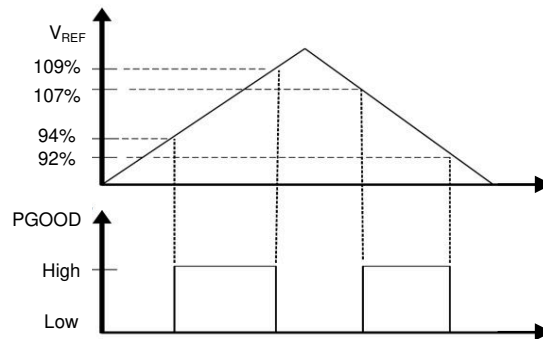
図 6-9. Power-Good Flag

6.3.10 Overcurrent and Short-Circuit Protection

The LMR14050-Q1 is protected from over current condition by cycle-by-cycle current limiting on the peak current of the high-side MOSFET. High-side MOSFET over-current protection is implemented by the nature of the Peak Current Mode control. The high-side switch current is compared to the output of the Error Amplifier (EA) minus slope compensation every switching cycle. Please refer to Functional Block Diagram for more details. The peak current of high-side switch is limited by a clamped maximum peak current threshold which is constant. So the peak current limit of the high-side switch is not affected by the slope compensation and remains constant over the full duty cycle range.

The LMR14050-Q1 also implements a frequency fold-back to protect the converter in severe over-current or short conditions. The oscillator frequency is divided by 2, 4, and 8 as the FB pin voltage decrease to 75%, 50%, 25% of V_{REF}. The frequency fold-back increases the off time by increasing the period of the switching cycle, so that it provides more time for the inductor current to ramp down and leads to a lower average inductor current. Lower frequency also means lower switching loss. Frequency fold-back reduces power dissipation and prevents overheating and potential damage to the device.

6.3.11 Overvoltage Protection

The LMR14050-Q1 employs an output overvoltage protection (OVP) circuit to minimize voltage overshoot when recovering from output fault conditions or strong unload transients in designs with low output capacitance. The OVP feature minimizes output overshoot by turning off high-side switch immediately when FB voltage reaches to the rising OVP threshold which is nominally 109% of the internal voltage reference V_{REF}. When the FB voltage drops below the falling OVP threshold which is nominally 107% of V_{REF}, the high-side MOSFET resumes normal operation.

6.3.12 Thermal Shutdown

The LMR14050-Q1 provides an internal thermal shutdown to protect the device when the junction temperature exceeds 170 °C (typical). The high-side MOSFET stops switching when thermal shundown activates. Once the die temperature falls below 158 °C (typical), the device reinitiates the power up sequence controlled by the internal soft-start circuitry.

6.4 Device Functional Modes

6.4.1 Shutdown Mode

The EN pin provides electrical ON and OFF control for the LMR14050-Q1. When V_{EN} is below 1.0 V, the device is in shutdown mode. The switching regulator is turned off and the quiescent current drops to 1.0 µA typically. The LMR14050-Q1 also employs undervoltage lockout protection. If V_{IN} voltage is below the UVLO level, the regulator is turned off.

6.4.2 Active Mode

The LMR14050-Q1 is in active mode when V_{EN} is above the precision enable threshold and V_{IN} is above the UVLO level. The simplest way to enable the LMR14050-Q1 is to connect the EN pin to VIN pin. This action allows self startup when the input voltage is in the operation range: 4.0 V to 40 V. Please refer to *セクション 6.3.6* for details on setting these operating levels.

In active mode, depending on the load current, the LMR14050-Q1 is in one of three modes:

1. Continuous conduction mode (CCM) with fixed switching frequency when load current is above half of the peak-to-peak inductor current ripple.
2. Discontinuous conduction mode (DCM) with fixed switching frequency when load current is lower than half of the peak-to-peak inductor current ripple in CCM operation.
3. Sleep-mode when internal COMP voltage drop to 400 mV at very light load.

6.4.3 CCM Mode

CCM operation is employed in the LMR14050-Q1 when the load current is higher than half of the peak-to-peak inductor current. In CCM operation, the frequency of operation is fixed, output voltage ripple is at a minimum in this mode and the maximum output current of 5 A can be supplied by the LMR14050-Q1.

6.4.4 Light Load Operation

When the load current is lower than half of the peak-to-peak inductor current in CCM, the LMR14050-Q1 operates in DCM. At even lighter current loads, Sleep mode is activated to maintain high efficiency operation by reducing switching and gate drive losses.

7 Application and Implementation

7.1 Application Information

The LMR14050-Q1 is a step down DC-to-DC regulator. The LMR14050-Q1 is typically used to convert a higher DC voltage to a lower DC voltage with a maximum output current of 5 A. The following design procedure can be used to select components for the LMR14050-Q1. This section presents a simplified discussion of the design process.

7.2 Typical Application

The LMR14050-Q1 only requires a few external components to convert from wide voltage range supply to a fixed output voltage. A schematic of 5 V / 5 A application circuit based on LMR14050-Q1 in SO-8 package is shown in 図 7-1. The external components have to fulfill the needs of the application, but also the stability criteria of the device's control loop.
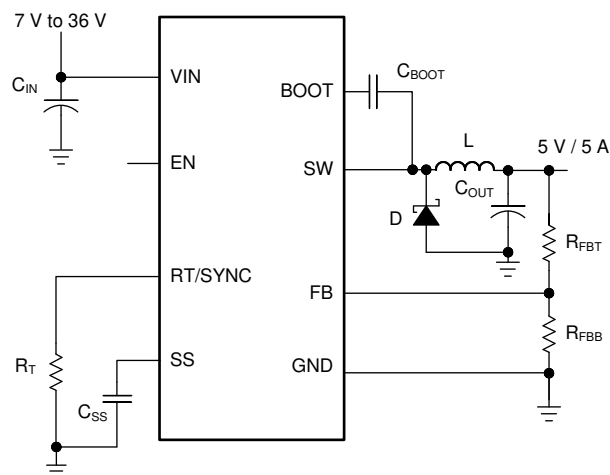
図 7-1. Application Circuit, 5V Output

7.2.1 Design Requirements

This example details the design of a high frequency switching regulator using ceramic output capacitors. A few parameters must be known to start the design process. These parameters are typically determined at the system level:

表 7-1. Design Parameters

Input Voltage, V_{IN}	7 V to 36 V, Typical 12 V
Output Voltage, V_{OUT}	5.0 V
Maximum Output Current I_{O_MAX}	5 A
Transient Response 0.5 A to 5 A	5%
Output Voltage Ripple	50 mV
Input Voltage Ripple	400 mV
Switching Frequency f_{SW}	300 kHz
Soft-start time	5 ms

7.2.2 Detailed Design Procedure

7.2.2.1 Output Voltage Set-Point

The output voltage of LMR14050-Q1 is externally adjustable using a resistor divider network. The divider network is comprised of top feedback resistor R_{FBT} and bottom feedback resistor R_{FBB}. 式 7 is used to determine the output voltage:

$$R_{FBT} = \frac{V_{OUT} - 0.75}{0.75} \times R_{FBB} \tag{7}$$

Choose the value of R_{FBT} to be 100 kΩ. With the desired output voltage set to 5 V and the V_{FB} = 0.75 V, the R_{FBB} value can then be calculated using 式 7. The formula yields to a value 17.65 kΩ. Choose the closest available value of 17.8 kΩ for R_{FBB}.

7.2.2.2 Switching Frequency

For desired frequency, use 式 8 to calculate the required value for R_T.

$$R_T(k\Omega) = 42904 \times f_{SW}(kHz)^{-1.088} \tag{8}$$

For 300 kHz, the calculated R_T is 86.57 kΩ and standard value 86.6 kΩ can be used to set the switching frequency at 300 kHz.

7.2.2.3 Output Inductor Selection

The most critical parameters for the inductor are the inductance, saturation current and the RMS current. The inductance is based on the desired peak-to-peak ripple current Δi_L. Because the ripple current increases with the input voltage, the maximum input voltage is always used to calculate the minimum inductance L_{MIN}. Use 式 10 to calculate the minimum value of the output inductor. K_{IND} is a coefficient that represents the amount of inductor ripple current relative to the maximum output current. A reasonable value of K_{IND} must be 20% – 40%. During an instantaneous short or over current operation event, the RMS and peak inductor current can be high. The inductor current rating must be higher than current limit.

$$\Delta i_L = \frac{V_{OUT} \times (V_{IN\_MAX} - V_{OUT})}{V_{IN\_MAX} \times L \times f_{SW}} \tag{9}$$

$$L_{MIN} = \frac{V_{IN\_MAX} - V_{OUT}}{I_{OUT} \times K_{IND}} \times \frac{V_{OUT}}{V_{IN\_MAX} \times f_{SW}} \tag{10}$$

In general, choosing lower inductance in switching power supplies is preferable, because choosing lower inductance usually corresponds to faster transient response, smaller DCR, and reduced size for more compact designs. But too low of an inductance can generate too large of an inductor current ripple such that over current protection at the full load can be falsely triggered. Too low of an inductance also generates more conduction loss because the RMS current is slightly higher. Larger inductor current ripple also implies larger output voltage ripple with same output capacitors. With peak current mode control, TI does not recommend to have too small of an inductor current ripple. A larger peak current ripple improves the comparator signal to noise ratio.

For this design example, choose K_{IND} = 0.4, the minimum inductor value is calculated to be 7.17 µH, and a nearest standard value is chosen: 8.2 µH. A standard 8.2 µH ferrite inductor with a capability of 6 A RMS current and 9 A saturation current can be used.

7.2.2.4 Output Capacitor Selection

The output capacitors, C_{OUT}, must be chosen with care because the output capacitors directly affect the steady state output voltage ripple, loop stability and the voltage over, undershoot during load current transients.

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The output ripple is essentially composed of two parts. One is caused by the inductor current ripple going through the Equivalent Series Resistance (ESR) of the output capacitors:

$$\Delta V_{OUT\_ESR} = \Delta i_L \times ESR = K_{IND} \times I_{OUT} \times ESR \tag{11}$$

The other is caused by the inductor current ripple charging and discharging the output capacitors:

$$\Delta V_{OUT\_C} = \frac{\Delta i_L}{8 \times f_{SW} \times C_{OUT}} = \frac{K_{IND} \times I_{OUT}}{8 \times f_{SW} \times C_{OUT}} \tag{12}$$

The two components in the voltage ripple are not in phase, so the actual peak-to-peak ripple is smaller than the sum of two peaks.

Output capacitance is usually limited by transient performance specifications if the system requires tight voltage regulation with presence of large current steps and fast slew rate. When a fast large load increase happens, output capacitors provide the required charge before the inductor current can slew up to the appropriate level. The regulator control loop usually needs three or more clock cycles to respond to the output voltage droop. The output capacitance must be large enough to supply the current difference for three clock cycles to maintain the output voltage within the specified range. 式 13 shows the minimum output capacitance needed for specified output undershoot. When a sudden large load decrease happens, the output capacitors absorb energy stored in the inductor. The catch diode cannot sink current so the energy stored in the inductor results in an output voltage overshoot. 式 14 calculates the minimum capacitance required to keep the voltage overshoot within a specified range.

$$C_{OUT} > \frac{3 \times (I_{OH} - I_{OL})}{f_{SW} \times V_{US}} \tag{13}$$

$$C_{OUT} > \frac{I_{OH}^2 - I_{OL}^2}{(V_{OUT} + V_{OS})^2 - V_{OUT}^2} \times L \tag{14}$$

where

- K_{IND} = Ripple ratio of the inductor ripple current ($\Delta i_L / I_{OUT}$)
- I_{OL} = Low level output current during load transient
- I_{OH} = High level output current during load transient
- V_{US} = Target output voltage undershoot
- V_{OS} = Target output voltage overshoot

For this design example, the target output ripple is 50 mV. Presuppose $\Delta V_{OUT\_ESR} = \Delta V_{OUT\_C} = 50$ mV, and chose $K_{IND} = 0.4$. 式 11 yields ESR no larger than 25 mΩ and 式 12 yields C_{OUT} no smaller than 33.3 µF. For the target over, undershoot range of this design, $V_{US} = V_{OS} = 5\% \times V_{OUT} = 250$ mV. The C_{OUT} can be calculated to be no smaller than 180 µF and 79.2 µF by 式 13 and 式 14 respectively. In summary, the most stringent criteria for the output capacitor is 180 µF. Four 47 µF, 16 V, X7R ceramic capacitors with 5 mΩ ESR are used in parallel .

7.2.2.5 *Schottky Diode Selection*

The breakdown voltage rating of the diode is preferred to be 25% higher than the maximum input voltage. The current rating for the diode must be equal to the maximum output current for best reliability in most applications. In cases where the input voltage is much greater than the output voltage the average diode current is lower. In this case, using a diode with a lower average current rating, approximately (1-D) × I_{OUT}, is possible. However, the peak current rating must be higher than the maximum load current. A 5 A to 7 A rated diode is a good starting point.

7.2.2.6 *Input Capacitor Selection*

The LMR14050-Q1 device requires high frequency input decoupling capacitors and a bulk input capacitor, depending on the application. The typical recommended value for the high frequency decoupling capacitor is 4.7 µF to 10 µF. A high-quality ceramic capacitor type X5R or X7R with sufficiency voltage rating is recommended. To compensate the derating of ceramic capacitors, a voltage rating of twice the maximum input voltage is recommended. Additionally, some bulk capacitance can be required, especially if the LMR14050-Q1 circuit is not located within approximately 5 cm from the input voltage source. This capacitor is used to provide damping to the voltage spike due to the lead inductance of the cable or the trace. For this design, two 2.2 µF, X7R ceramic capacitors rated for 100 V are used. Use a 0.1 µF for high-frequency filtering and place as close as possible to the device pins.

7.2.2.7 *Bootstrap Capacitor Selection*

Every LMR14050-Q1 design requires a bootstrap capacitor (C_{BOOT}). The recommended capacitor is 0.1 µF and rated 16 V or higher. The bootstrap capacitor is located between the SW pin and the BOOT pin. The bootstrap capacitor must be a high-quality ceramic type with an X7R or X5R grade dielectric for temperature stability.

7.2.2.8 Soft-start Capacitor Selection

Use 式 15 to calculate the soft-start capacitor value:

$$C_{SS}(nF) = \frac{t_{SS}(ms) \times I_{SS}(\mu A)}{V_{REF}(V)}$$

(15)

where

- C_{SS} = Soft-start capacitor value
- I_{SS} = Soft-start charging current (3 µA)
- t_{SS} = Desired soft-start time

For the desired soft-start time of 5 ms and soft-start charging current of 3.0 µA, 式 15 yields a soft-start capacitor value of 20 nF, a standard 22 nF ceramic capacitor is used.

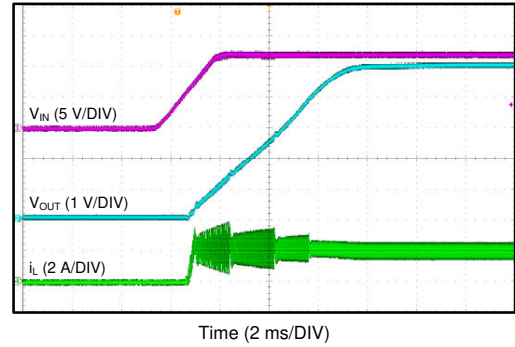For design with LMR14050-Q1 in WSON package, the maximum value of C_{SS} is 4.7 nF.

7.2.3 Application Curves

Unless otherwise specified the following conditions apply: V_{IN} = 12 V, f_{SW} = 300 kHz, L = 6.5 µH, C_{OUT} = 47 µF × 4, T_A = 25°C
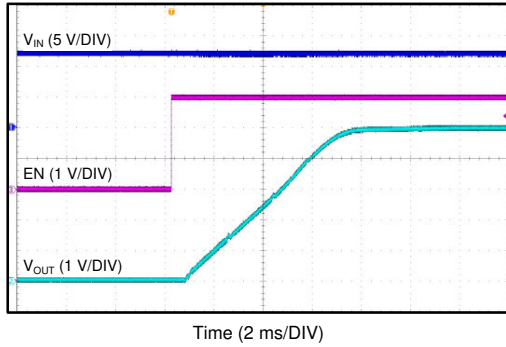
V_{IN} = 12 V	V_{OUT} = 5 V	I_{OUT} = 2 A

図 7-2. Start-up By EN

V_{IN} = 12 V	V_{OUT} = 5 V	I_{OUT} = 2 A

図 7-3. Start-up By V_{IN}
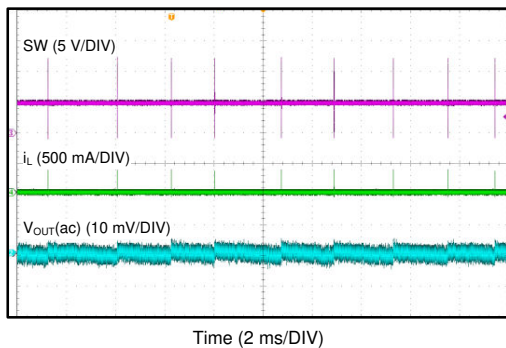
V_{IN} = 12 V	V_{OUT} = 5 V	I_{OUT} = 0 A

図 7-4. Sleep-mode
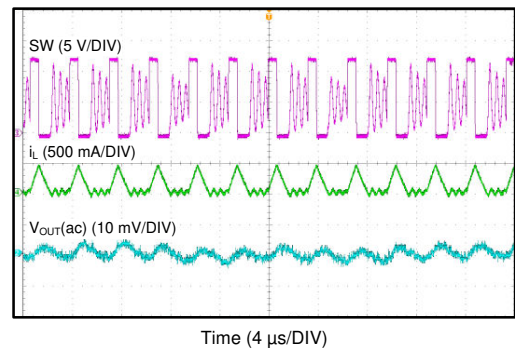
V_{IN} = 12 V	V_{OUT} = 5 V	I_{OUT} = 100 mA
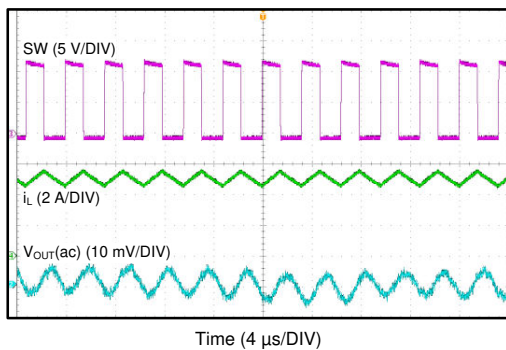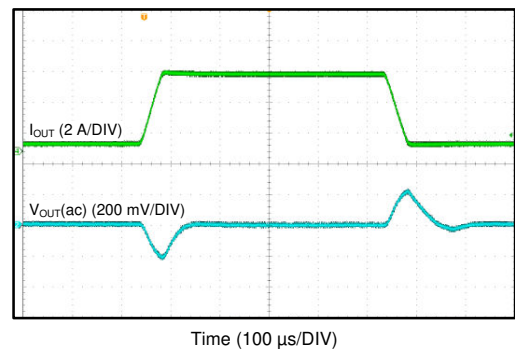
図 7-5. DCM Mode

図 7-6. CCM Mode

I_{OUT}: 10% → 100% of 5 A   Slew rate = 100 mA/µs

図 7-7. Load Transient

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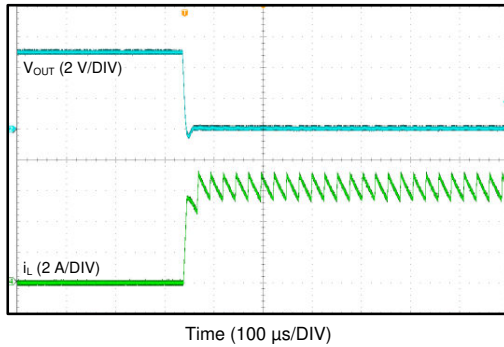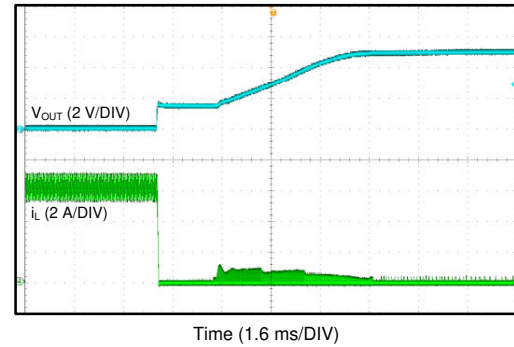
図 7-8. Output Short

図 7-9. Output Short Recovery

7.3 Power Supply Recommendations

The LMR14050-Q1 is designed to operate from an input voltage supply range between 4 V and 40 V. This input supply must be able to withstand the maximum input current and maintain a stable voltage. The resistance of the input supply rail must be low enough that an input current transient does not cause a high enough drop at the LMR14050-Q1 supply voltage that can cause a false UVLO fault triggering and system reset. If the input supply is located more than a few inches from the LMR14050-Q1, additional bulk capacitance can be required in addition to the ceramic input capacitors. The amount of bulk capacitance is not critical, but a 47 µF or 100 µF electrolytic capacitor is a typical choice .

7.4 Layout

7.4.1 Layout Guidelines

Layout is a critical portion of good power supply design. The following guidelines help users design a PCB with the best power conversion performance, thermal performance, and minimized generation of unwanted EMI.

1. The feedback network, resistor R_{FBT} and R_{FBB}, must be kept close to the FB pin. V_{OUT} sense path away from noisy nodes and preferably through a layer on the other side of a shielding layer .
2. The input bypass capacitor C_{IN} must be placed as close as possible to the VIN pin and ground. Grounding for both the input and output capacitors must consist of localized top side planes that connect to the GND pin and PAD .
3. The inductor L must be placed close to the SW pin to reduce magnetic and electrostatic noise.
4. The output capacitor, C_{OUT} must be placed close to the junction of L and the diode D. The L, D, and C_{OUT} trace must be as short as possible to reduce conducted and radiated noise and increase overall efficiency.
5. The ground connection for the diode, C_{IN}, and C_{OUT} must be as small as possible and tied to the system ground plane in only one spot (preferably at the C_{OUT} ground point) to minimize conducted noise in the system ground plane
6. For more detail on switching power supply layout considerations see SNVA021 Application Note AN-1149

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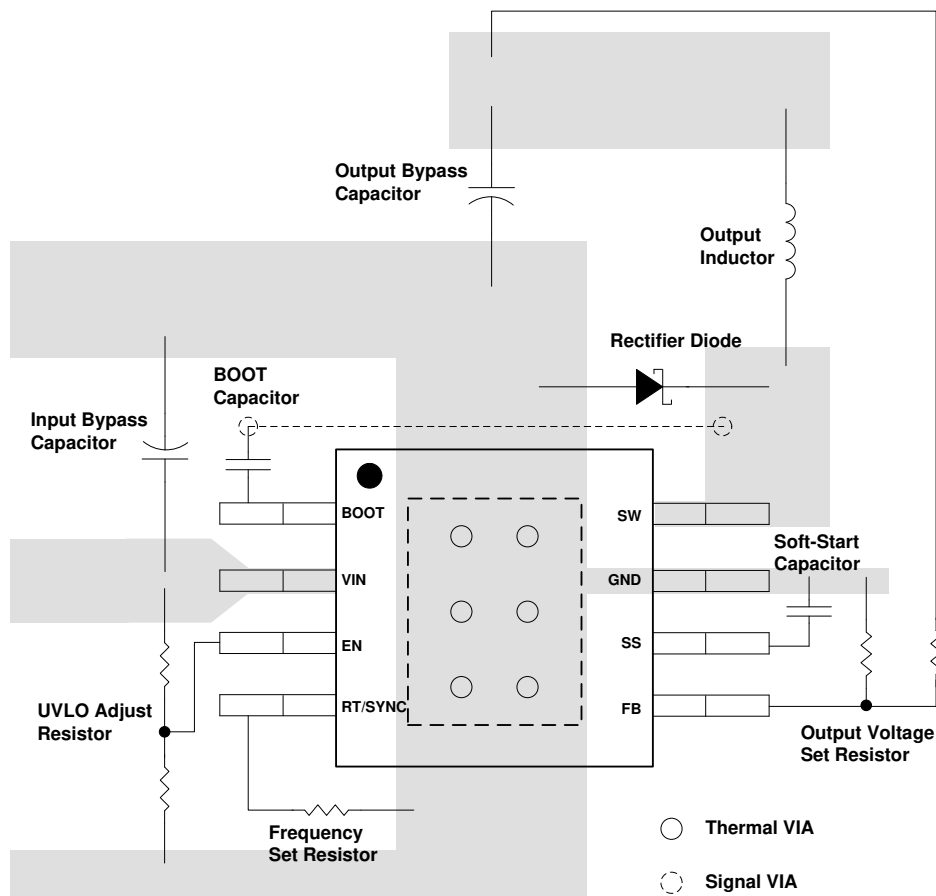English Data Sheet: SNVSAG2

7.4.2 Layout Example

図 7-10. Layout

8 Device and Documentation Support

8.1 Device Support

8.1.1 サード・パーティ製品に関する免責事項

サード・パーティ製品またはサービスに関するテキサス・インスツルメンツの出版物は、単独またはテキサス・インスツルメンツの製品、サービスと一緒に提供される場合に関係なく、サード・パーティ製品またはサービスの適合性に関する是認、サード・パーティ製品またはサービスの是認の表明を意味するものではありません。

8.2 Documentation Support

8.2.1 Related Documentation

For related documentation see the following:

Texas Instruments, *AN-1149 Layout Guidelines for Switching Power Supplies* application note

8.2.2 Related Products

Part Number	V_{IN} (V)	I_{OUT} (A)	Comments
LMR14020-Q1	4.0 - 40	2	Non-synchronous step-down converter, I_Q = 40 µA, sleep mode, spread spectrum, SO-8 or WSON-10 package
LMR14030-Q1	4.0 - 40	3.5	

8.3 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

8.4 サポート・リソース

テキサス・インスツルメンツ E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計で必要な支援を迅速に得ることができます。

リンクされているコンテンツは、各寄稿者により「現状のまま」提供されるものです。これらはテキサス・インスツルメンツの仕様を構成するものではなく、必ずしもテキサス・インスツルメンツの見解を反映したものではありません。テキサス・インスツルメンツの使用条件を参照してください。

8.5 Trademarks

PowerPAD™ and テキサス・インスツルメンツ E2E™ are trademarks of Texas Instruments.
SIMPLE SWITCHER® is a registered trademark of Texas Instruments.
すべての商標は、それぞれの所有者に帰属します。

8.6 静電気放電に関する注意事項

この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

8.7 用語集

テキサス・インスツルメンツ用語集　　この用語集には、用語や略語の一覧および定義が記載されています。

9 Revision History

Changes from Revision A (February 2016) to Revision B (December 2024)   **Page**

Changes from Revision * (November 2015) to Revision A (February 2016)   **Page**

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMR14050QDPRRQ1	Active	Production	WSON (DPR) | 10	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LMR 14050Q
LMR14050QDPRRQ1.A	Active	Production	WSON (DPR) | 10	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LMR 14050Q
LMR14050QDPRTQ1	Active	Production	WSON (DPR) | 10	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LMR 14050Q
LMR14050QDPRTQ1.A	Active	Production	WSON (DPR) | 10	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LMR 14050Q
LMR14050SQDDAQ1	Active	Production	SO PowerPAD (DDA) | 8	75 | TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	14050Q
LMR14050SQDDAQ1.A	Active	Production	SO PowerPAD (DDA) | 8	75 | TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	14050Q
LMR14050SQDDARQ1	Active	Production	SO PowerPAD (DDA) | 8	2500 | LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	14050Q
LMR14050SQDDARQ1.A	Active	Production	SO PowerPAD (DDA) | 8	2500 | LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	14050Q
LMR14050SQDPRRQ1	Active	Production	WSON (DPR) | 10	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LMR 1405SQ
LMR14050SQDPRRQ1.A	Active	Production	WSON (DPR) | 10	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LMR 1405SQ
LMR14050SQDPRTQ1	Active	Production	WSON (DPR) | 10	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LMR 1405SQ
LMR14050SQDPRTQ1.A	Active	Production	WSON (DPR) | 10	250 | SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	LMR 1405SQ
LMR14050SSQDDAQ1	Active	Production	SO PowerPAD (DDA) | 8	75 | TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1405SQ
LMR14050SSQDDAQ1.A	Active	Production	SO PowerPAD (DDA) | 8	75 | TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1405SQ
LMR14050SSQDDARQ1	Active	Production	SO PowerPAD (DDA) | 8	2500 | LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1405SQ
LMR14050SSQDDARQ1.A	Active	Production	SO PowerPAD (DDA) | 8	2500 | LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	1405SQ

(1) **Status:** For more details on status, see our product life cycle.

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LMR14050-Q1 :

• Catalog : LMR14050

NOTE: Qualified Version Definitions:

    • Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMR14050QDPRRQ1	WSON	DPR	10	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
LMR14050QDPRTQ1	WSON	DPR	10	250	180.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
LMR14050SQDDARQ1	SO PowerPAD	DDA	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LMR14050SQDPRRQ1	WSON	DPR	10	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
LMR14050SQDPRTQ1	WSON	DPR	10	250	180.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
LMR14050SSQDDARQ1	SO PowerPAD	DDA	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMR14050QDPRRQ1	WSON	DPR	10	3000	346.0	346.0	33.0
LMR14050QDPRTQ1	WSON	DPR	10	250	210.0	185.0	35.0
LMR14050SQDDARQ1	SO PowerPAD	DDA	8	2500	366.0	364.0	50.0
LMR14050SQDPRRQ1	WSON	DPR	10	3000	346.0	346.0	33.0
LMR14050SQDPRTQ1	WSON	DPR	10	250	210.0	185.0	35.0
LMR14050SSQDDARQ1	SO PowerPAD	DDA	8	2500	366.0	364.0	50.0

TUBE

T - Tube height

L - Tube length

W - Tube width

B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
LMR14050SQDDAQ1	DDA	HSOIC	8	75	517	7.87	635	4.25
LMR14050SQDDAQ1.A	DDA	HSOIC	8	75	517	7.87	635	4.25
LMR14050SSQDDAQ1	DDA	HSOIC	8	75	517	7.87	635	4.25
LMR14050SSQDDAQ1.A	DDA	HSOIC	8	75	517	7.87	635	4.25

DDA (R−PDSO−G8)   PowerPAD ™ PLASTIC SMALL−OUTLINE

THERMAL PAD

SIZE AND SHAPE SHOWN
ON SEPARATE SHEET

1,27

$\frac{0,51}{0,31}$ ⊕ 0,25Ⓜ

$\frac{4,00}{3,80}$ $\frac{6,20}{5,80}$

$\frac{5,00}{4,80}$

0,20 NOM

Gage Plane

0°−8°

0,25

$\frac{1,27}{0,40}$

1,70 MAX

$\frac{0,15}{0,00}$

Seating Plane

⌀ 0,10

4202561/F 12/11

NOTES: A.   All linear dimensions are in millimeters.   Dimensioning and tolerancing per ASME Y14.5−1994.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion not to exceed 0,15.
         D.   This package is designed to be soldered to a thermal pad on the board.   Refer to Technical Brief, PowerPad
              Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding
              recommended board layout.   This document is available at www.ti.com <http://www.ti.com>.
         E.   See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
         F.   This package complies to JEDEC MS−012 variation BA

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DDA (R-PDSO-G8)   PowerPAD™ PLASTIC SMALL OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.
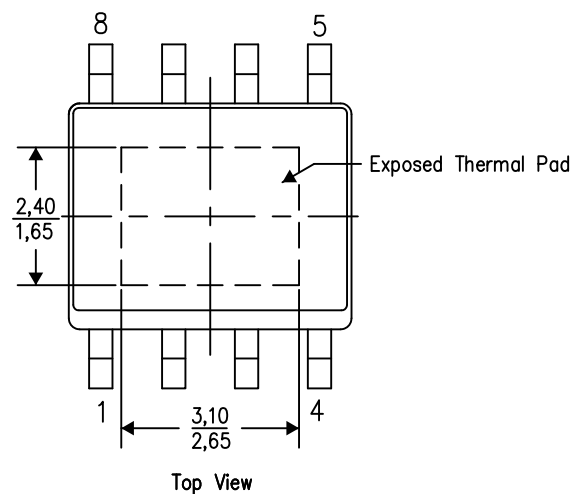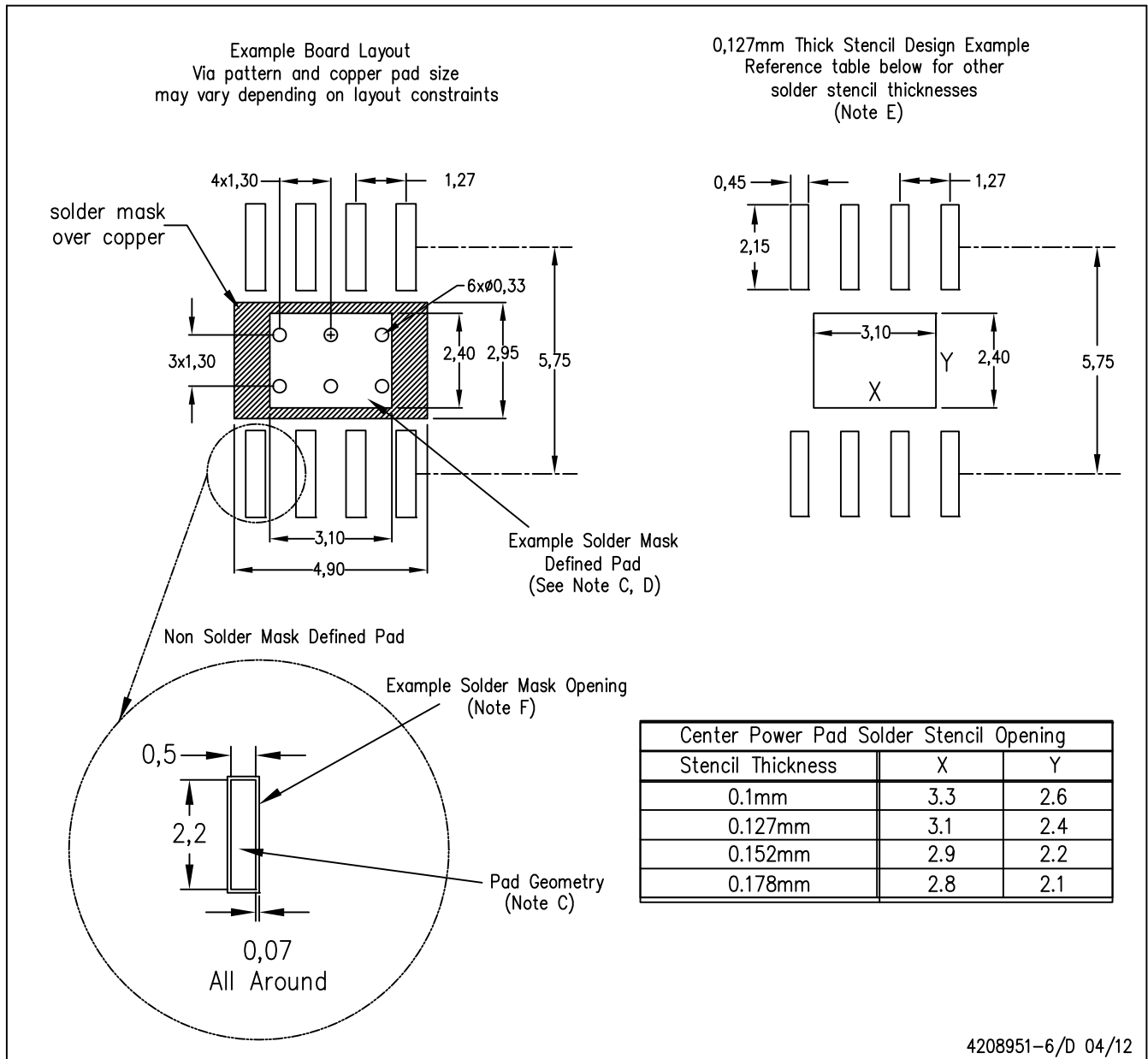

Exposed Thermal Pad Dimensions

4206322-6/L 05/12

NOTE: A. All linear dimensions are in millimeters

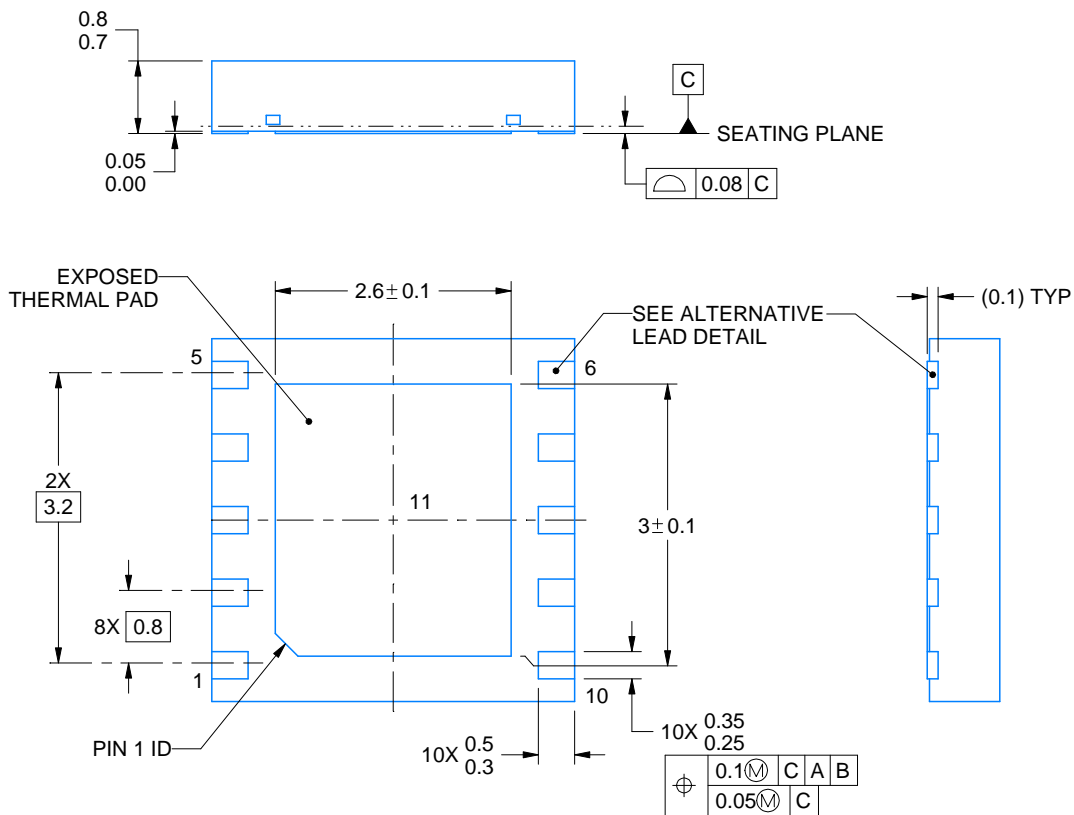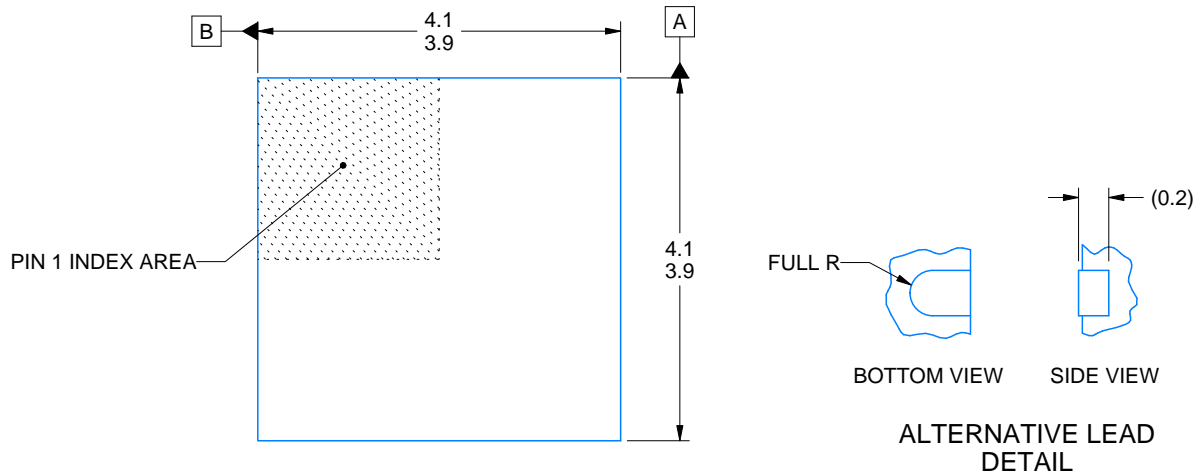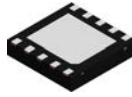PowerPAD is a trademark of Texas Instruments

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DDA (R—PDSO—G8)   PowerPAD™ PLASTIC SMALL OUTLINE

Example Board Layout
Via pattern and copper pad size
may vary depending on layout constraints

0,127mm Thick Stencil Design Example
Reference table below for other
solder stencil thicknesses
(Note E)

solder mask
over copper

4x1,30   1,27

6x∅0,33

3x1,30

2,40 2,95   5,75

3,10

4,90

Example Solder Mask
Defined Pad
(See Note C, D)

Non Solder Mask Defined Pad

0,45   1,27

2,15

3,10

X   Y   2,40   5,75

Example Solder Mask Opening
(Note F)

0,5

2,2

0,07
All Around

Pad Geometry
(Note C)

Center Power Pad Solder Stencil Opening		
Stencil Thickness	X	Y
0.1mm	3.3	2.6
0.127mm	3.1	2.4
0.152mm	2.9	2.2
0.178mm	2.8	2.1

4208951—6/D 04/12

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC—7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad
Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets
for specific thermal information, via requirements, and recommended board layout. These documents are available at
www.ti.com <http://www.ti.com>. Publication IPC—7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric
metal load solder paste. Refer to IPC—7525 for other stencil recommendations.
F. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
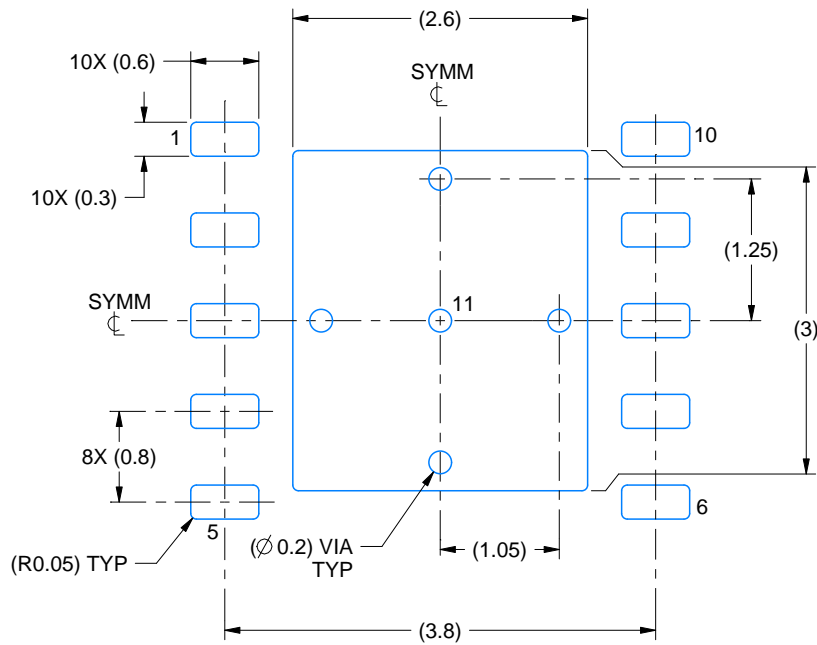
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B | 4.1 / 3.9 | A

PIN 1 INDEX AREA

4.1 / 3.9

(0.2)

FULL R

BOTTOM VIEW   SIDE VIEW

ALTERNATIVE LEAD DETAIL

0.8 / 0.7

C

SEATING PLANE

0.05 / 0.00

⌒ | 0.08 | C

EXPOSED THERMAL PAD

2.6 ± 0.1

SEE ALTERNATIVE LEAD DETAIL

(0.1) TYP

5

6

11

3 ± 0.1

2X [3.2]

8X [0.8]

1

10

PIN 1 ID

10X 0.5 / 0.3

10X 0.35 / 0.25

⊕ | 0.1 Ⓜ | C | A | B
  | 0.05 Ⓜ | C

4218856/B   01/2021

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

10X (0.6)

(2.6)

SYMM

1

10X (0.3)

10

(1.25)

SYMM

11

(3)

8X (0.8)

6

5

(R0.05) TYP

(Ø 0.2) VIA
TYP

(1.05)

(3.8)

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

0.07 MAX
ALL AROUND

EXPOSED
METAL

SOLDER MASK
OPENING

METAL
EDGE

NON SOLDER MASK
DEFINED
(PREFERRED)

0.07 MIN
ALL AROUND

EXPOSED
METAL

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

SOLDER MASK
DEFINED
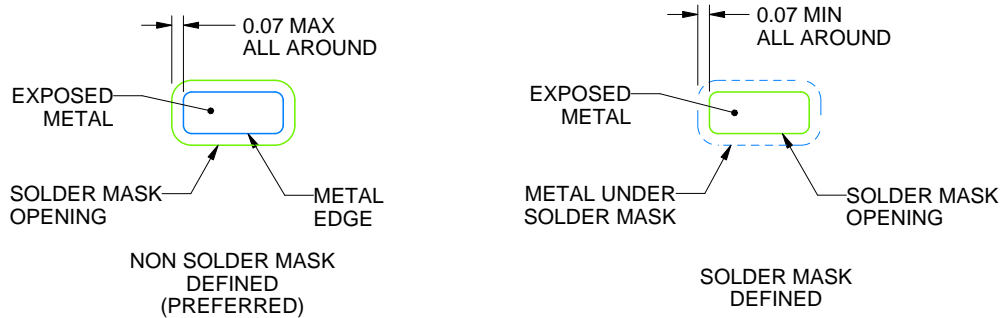
SOLDER MASK DETAILS

4218856/B   01/2021

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

SYMM

10X (0.6)

METAL TYP

(0.68)

1

10

10X (0.3)

(0.76)

SYMM

11

8X (0.8)

4X (1.31)

5

6

(R0.05) TYP

4X (1.15)

(3.8)
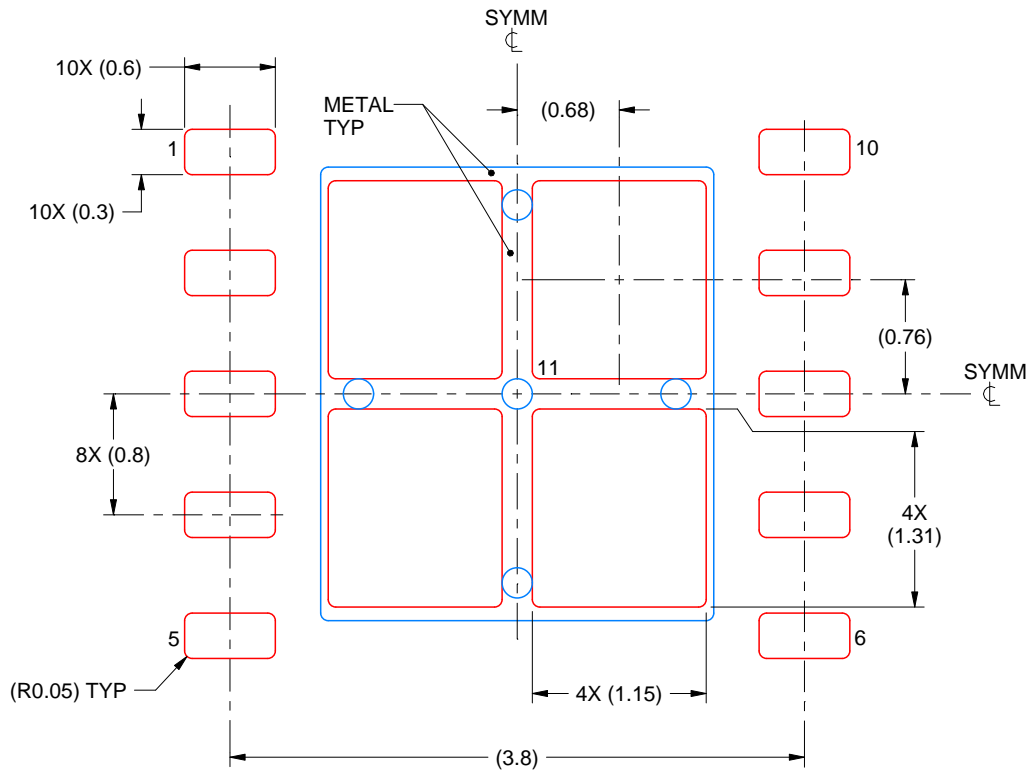
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 11:
77% PRINTED SOLDER COVERAGE BY AREA
SCALE:20X

4218856/B 01/2021

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.